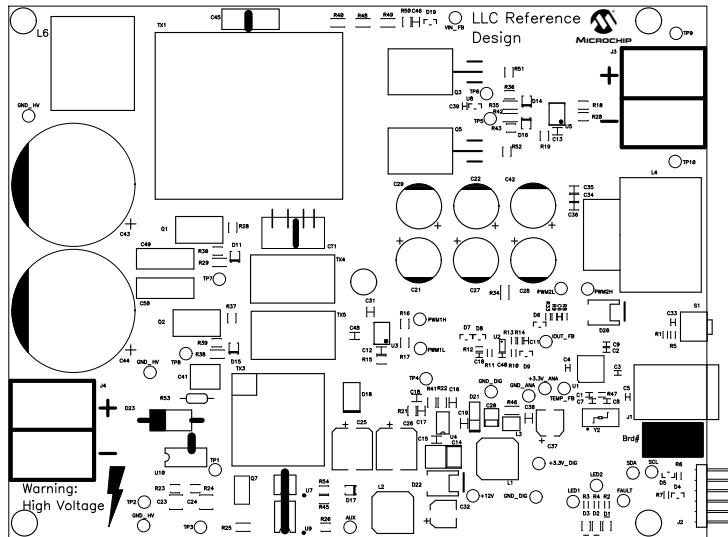


A B C D E F



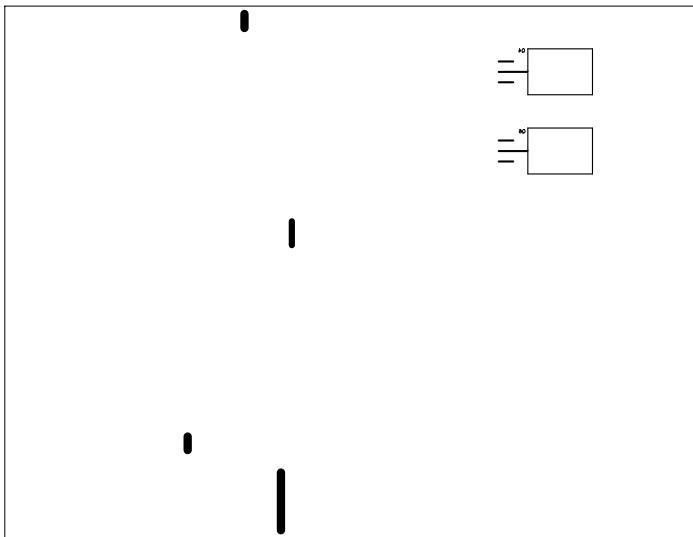
Assembly Notes:

1. All materials and components are to RoHS compliant
2. All unused component holes/pads are to be free of solder
3. All components are to be mounted flush to the board
4. Finished boards are to be free of all residues
5. All TH part leads should not exceed 0.8 mils

Title LLC Reference Design		
Size	02-07149	Rev 0.2
C		
Engineer: A. Dumais	Date: Tue Jul 26, 2016	Drawn by: M. Curran
Filename: 05-07149_R0.2.pcb	Sheet 1 of 1	

A B C D E F

A B C D E F



Title		LLC Reference Design	Rev
Size		MICROCHIP	0.2
C			
Engineer:	A. Dumais	Drawn by:	M. Curran
Date:	Tue Jul 26, 2016	Filename:	05-07149_R0.2.pdfsheet 1 of 1

A B C D E F